



## **Future Coat Technology**

### **STRIPEX HD COPPER PLUS**

#### **Introduction:**

**STRIPEX HD COPPER PLUS** can be operated under the room temperature, which can remove the copper and silver plating layer on the nickel or nickel alloy, without damaging the surface of matrix metal, to achieve to maintain the brightness of silver plating layer.

The process of **STRIPEX HD COPPER PLUS** does not need to use the power, which can be disposed with spraying or impregnating methods.

#### **Necessary equipment:**

**Bath:** PVC, PP or stainless steel bath

**Heater:** Stainless steel or quartz heating pen should be utilized with mixture

#### **Operative conditions:**

**Temperature:** 30 °C (20-40°C)

#### **Solution composition:**

**STRIPEX HP COPPER PLUS**      11.3g/L

**KCN:**                                      28.0g/L

**KOH**                                         5.6g/L

#### **Preparation procedure:**

- 1. 1/5 volume pure water is filled into it, and heated to be 50-60°C;**
- 2. KOH is added, and then it is mixed to be even;**
- 3. KCN is added, and then it is mixed to be even;**
- 4. STRIPEX HD COPPER is added, and it is mixed to be completely dissolved; therefore,**

**The good mixture system is require**

- 5. Pure water is filled to adjust the solution level to be the standard level.**

**Velocity of stripping:**

**Under the situation that copper content is less than 2g/L, copper planting layer with**

**0.1 ~0.2um can be removed completely within 20 seconds.**

### **Special statement**

**The proposals in this instruction or the suggestions for our product are based on our reliable experiments and data. However, it is impossible for us to control operator and therefore we shall not guarantee and hold the Responsibility for the adverse outcomes. All of data in the instruction are not regarded as the evidence of copyright infringement.**